



INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION #20606Generic Copy

Issue Date: 11-Aug-2014**TITLE:** Assembly and Test Expansion for NCP367OPMUEOTBG at Amkor, Philippines**PROPOSED FIRST SHIP DATE:** 11-Dec-2014**AFFECTED CHANGE CATEGORY(S):** Assembly and Test location**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**Contact your local ON Semiconductor Sales Office or <shilpa.rao@onsemi.com>**NOTIFICATION TYPE:**

Initial Product/Process Change Notification (IPCN)

First change notification sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change.

DESCRIPTION AND PURPOSE:

This is the Initial Product Notification announcing the expansion of Assembly and Test operations of the NCP367OPMUEOTBG to Amkor, Philippines (ATP) in order to meet high customer demand. ON Semiconductor will continue to utilize its current facility in Seremban, Malaysia for the assembly and test of the device.

Amkor, Philippines already conducts assembly and test for other QFN, SOIC, PLCC and additional devices for ON Semiconductor. Amkor's industry certifications include ISO-9001, ISO-14001 and TS-16949.

There will be no change in the physical package, electrical performance and reliability of the NCP367OPMUEOTBG as result of this expansion – the device will continue to meet or exceed ON Semi's specifications and standards.



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QUALIFICATION PLAN:

Estimated Date for Qualification Completion: 12/31/2014.
Samples should be available after completion of Qualification.

Full qualification testing will be performed as necessary. Reliability tests may include the following:

HTOL High Temp Op Life for 504 hrs. $T_j = 135^{\circ}\text{C}$
PC-Temp Cycle -65°C to $+150^{\circ}\text{C}$ for 500 cycles
PC-UHAST $130^{\circ}\text{C}/85\% \text{RH}$ for 96 hrs
PC-HAST $130^{\circ}\text{C}/85\% \text{RH}$ for 96 hrs
PC-SAT with MSL1 preconditioning at 260°C
Solderability with 8hrs steam age prior to test
ELFR $T_j = 125^{\circ}\text{C}$ for 48 hours
Wire Bond Pull
Wire Bond Shear
Die Shear
Electrical Temperature Characterization per ON Semi specifications

List of affected General Parts:

NCP367OPMUEOTBG